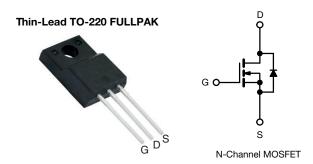
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FREE



EF Series Power MOSFET with Fast Body Diode



| PRODUCT SUMMA | RY | |
|--|------------------------|-------|
| V _{DS} (V) at T _J max. | 650 |) |
| R _{DS(on)} max. (Ω) at 25 °C | V _{GS} = 10 V | 0.176 |
| Q _g max. (nC) | 84 | |
| Q _{gs} (nC) | 14 | |
| Q _{gd} (nC) | 24 | |
| Configuration | Sing | le |

FEATURES

- Fast body diode MOSFET using E series technology
- Reduced t_{rr}, Q_{rr}, and I_{RRM}
- Low figure-of-merit (FOM): Ron x Qg
- Low input capacitance (Ciss)
- Increased robustness due to low Q_{rr}
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Telecommunications
 - Server and telecom power supplies
- - High intensity discharge (HID)
 - Light emitting diodes (LEDs)
- Consumer and computing
 - ATX power supplies
- Industrial
 - Welding
 - Battery chargers
- Renewable energy
 - Solar (PV inverters)
- Switch mode power suppliers (SMPS)
- Applications using the following topologies
 - LLC
 - Phase shifted bridge (ZVS)
 - 3-level inverter
 - AC/DC bridge

| ORDERING INFORMATION | |
|---------------------------------|--------------------------|
| Package | Thin-Lead TO-220 FULLPAK |
| Lead (Pb)-free | SiHA21N60EF-E3 |
| Lead (Pb)-free and halogen-free | SiHA21N60EF-GE3 |

| ABSOLUTE MAXIMUM RATINGS (T _C | = 25 °C, unl | ess otherwis | se noted) | | |
|--|--|---|-----------------------------------|-------------|-------|
| PARAMETER | | | SYMBOL | LIMIT | UNIT |
| Drain-source voltage | | V_{DS} | 600 | V | |
| Gate-source voltage | | | V_{GS} | ± 30 | V |
| Continuous dusin suggest (T. 150 °C) | \/ at 10 \/ | $T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$ | | 9 | |
| Continuous drain current (T _J = 150 °C) | V _{GS} at 10 V | T _C = 100 °C | I _D | 5 | Α |
| Pulsed drain current ^a | | | I _{DM} | 53 | |
| Linear derating factor | 0.28 W/°C | | | | |
| Single pulse avalanche energy b | | | E _{AS} | 367 | mJ |
| Maximum power dissipation | | | P_{D} | 35 | W |
| Operating junction and storage temperature range | | | T _J , T _{stg} | -55 to +150 | °C |
| Drain-source voltage slope | T _J = 125 °C | | -11.//-14 | 70 | V/ns |
| Reverse diode dV/dt ^d | | | dV/dt | 50 | V/IIS |
| Soldering recommendations (peak temperature) c | oldering recommendations (peak temperature) c for 10 s 300 | | °C | | |
| Mounting torque | M3 s | crew | | 0.6 | Nm |

- a. Repetitive rating; pulse width limited by maximum junction temperature b. $V_{DD}=50$ V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 5.1 A
- 1.6 mm from case
- d. $I_{SD} \le I_D$, $dI/dt = 900 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$



Vishay Siliconix

| THERMAL RESISTANCE RATINGS | | | | |
|----------------------------------|-------------------|------|------|------|
| PARAMETER | SYMBOL | TYP. | MAX. | UNIT |
| Maximum junction-to-ambient | R _{thJA} | - | 65 | °C/W |
| Maximum junction-to-case (drain) | R_{thJC} | - | 3.6 | C/VV |

| PARAMETER | SYMBOL | TES | T CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|---|-----------------------|--|---|------|-------|-------|---------|
| Static | | ^ | | | • | ı | |
| Drain-source breakdown voltage | V _{DS} | V _{GS} : | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$ | | - | - | V |
| V _{DS} temperature coefficient | $\Delta V_{DS}/T_{J}$ | Referenc | e to 25 °C, I _D = 1 mA | - | 0.59 | - | V/°C |
| Gate-source threshold voltage (N) | V _{GS(th)} | V _{DS} = | = V _{GS} , I _D = 250 μA | 2.0 | - | 4.0 | V |
| Gate-source leakage | 1 | V _{GS} = ± 20 V | | - | - | ± 100 | nA |
| Gate-source leakage | I _{GSS} | | $V_{GS} = \pm 30 \text{ V}$ | - | - | ± 1 | μΑ |
| Zero gate voltage drain current | | | $V_{DS} = 480 \text{ V}, V_{GS} = 0 \text{ V}$ | | - | 1 | μА |
| Zero gate voltage drain current | I _{DSS} | V _{DS} = 480 \ | $V_{\rm S} = 0 \ V_{\rm T} = 125 \ ^{\circ}{\rm C}$ | - | - | 500 | μΑ |
| Drain-source on-state resistance | R _{DS(on)} | V _{GS} = 10 V | I _D = 11 A | - | 0.153 | 0.176 | Ω |
| Forward transconductance | 9 _{fs} | V_{DS} | = 30 V, I _D = 11 A | - | 7 | - | S |
| Dynamic | | | | | | | |
| Input capacitance | C _{iss} | V _{GS} = 0 V, | | - | 2030 | - | |
| Output capacitance | C _{oss} | | $V_{DS} = 100 V,$ | - | 105 | - | |
| Reverse transfer capacitance | C_{rss} | | f = 1 MHz | - | 5 | - | |
| Effective output capacitance, energy related ^a | $C_{\text{o(er)}}$ | V _{GS} = 0 V, V _{DS} = 0 V to 480 V | | - | 86 | - | pF - |
| Effective output capacitance, time related ^b | $C_{o(tr)}$ | | | - | 299 | - | |
| Total gate charge | Qg | | | - | 56 | 84 | |
| Gate-source charge | Q _{gs} | V _{GS} = 10 V | | - | 14 | - | nC |
| Gate-drain charge | Q _{gd} | | | - | 24 | - | |
| Turn-on delay time | t _{d(on)} | | | - | 21 | 42 | |
| Rise time | t _r | V _{DD} = 480 V, I _D = 11 A | | - | 31 | 62 | ns |
| Turn-off delay time | t _{d(off)} | $R_g = 1$ | $R_g = 9.1 \Omega, V_{GS} = 10 V$ | | 59 | 89 | |
| Fall time | t _f | 1 | | - | 27 | 54 | |
| Gate input resistance | Rg | f = 1 MHz, open drain | | 0.2 | 0.56 | 1.2 | Ω |
| Drain-Source Body Diode Characteristic | es | | | | | | |
| Continuous source-drain diode current | I _S | MOSFET symbol showing the integral reverse p - n junction diode | | - | - | 21 | |
| Pulsed diode forward current | I _{SM} | | | - | - | 53 | A |
| Diode forward voltage | V _{SD} | T _J = 25 °C, I _S = 11 A, V _{GS} = 0 V | | - | 0.9 | 1.2 | V |
| Reverse recovery time | t _{rr} | | | - | 135 | 270 | ns |
| Reverse recovery charge | Q _{rr} | $T_J = 25 \text{ °C}, I_F = I_S = 11 \text{ A},$ $dI/dt = 100 \text{ A/}\mu\text{s}, V_R = 400 \text{ V}$ | | _ | 0.76 | 1.52 | μC |
| Reverse recovery current | I _{RRM} | | | - | 11 | - | A |

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

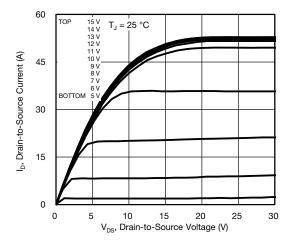


Fig. 1 - Typical Output Characteristics, T_J = 25 °C

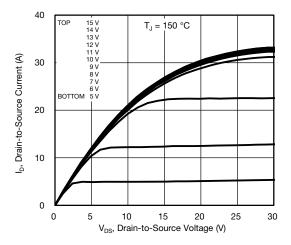


Fig. 2 - Typical Output Characteristics, T_J = 150 °C

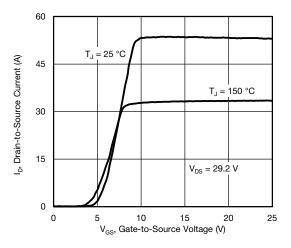


Fig. 3 - Typical Transfer Characteristics

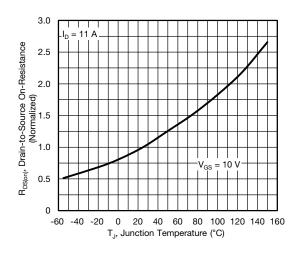


Fig. 4 - Normalized On-Resistance vs. Temperature

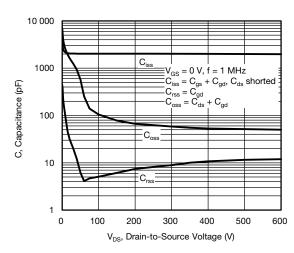


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

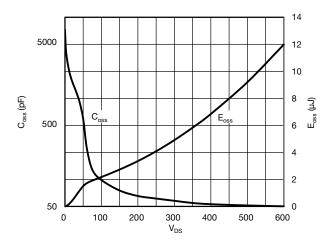


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



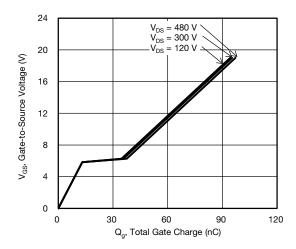


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

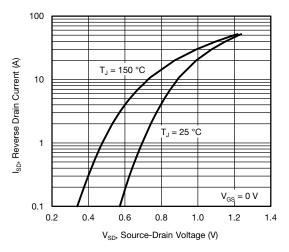


Fig. 8 - Typical Source-Drain Diode Forward Voltage

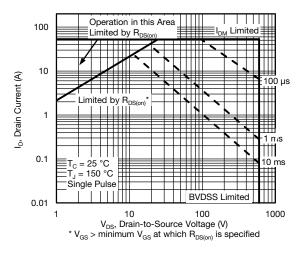


Fig. 9 - Maximum Safe Operating Area

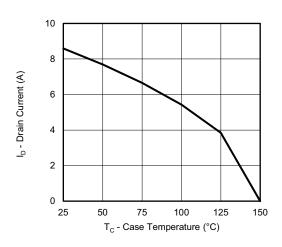


Fig. 10 - Maximum Drain Current vs. Case Temperature

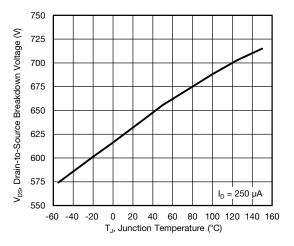


Fig. 11 - Typical Drain-to-Source Voltage vs. Temperature

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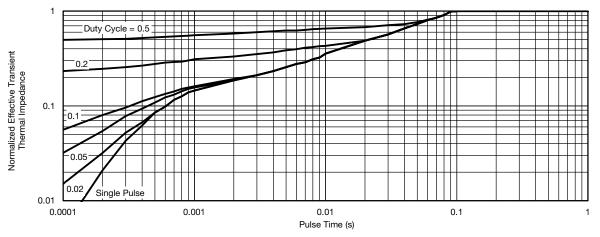


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

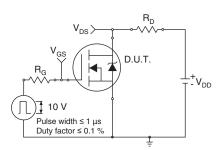


Fig. 13 - Switching Time Test Circuit

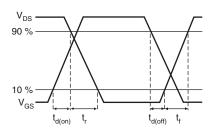


Fig. 14 - Switching Time Waveforms

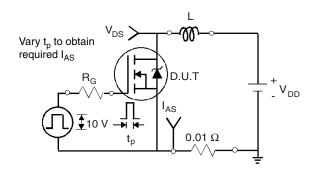


Fig. 15 - Unclamped Inductive Test Circuit

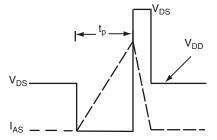


Fig. 16 - Unclamped Inductive Waveforms

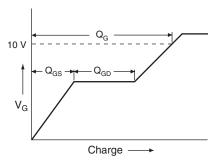


Fig. 17 - Basic Gate Charge Waveform

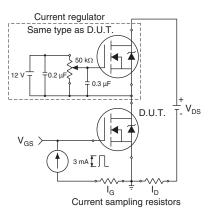
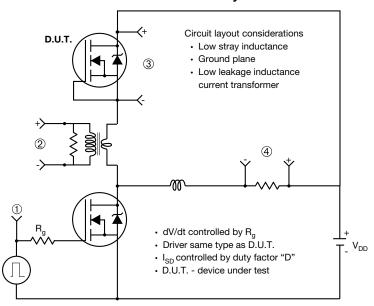


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



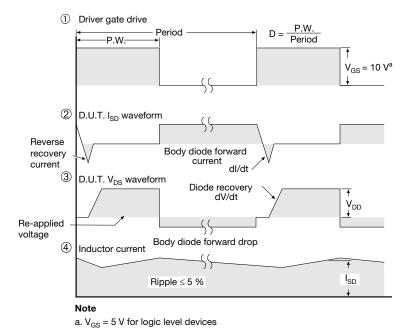
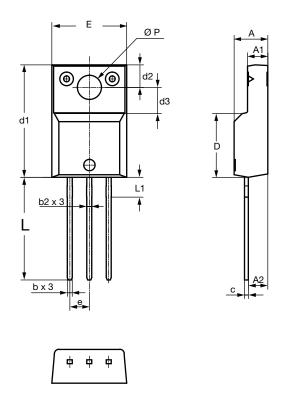


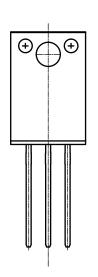
Fig. 19 - For N-Channel

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TO-220 FULLPAK Thin Lead





| | | DIMEN | ISIONS | |
|--------|--------|--------|--------|-------|
| SYMBOL | MILLIN | IETERS | INC | HES |
| | MIN. | MAX. | MIN. | MAX. |
| Α | 4.30 | 4.70 | 0.169 | 0.185 |
| A1 | 2.50 | 2.90 | 0.098 | 0.114 |
| A2 | 2.40 | 2.80 | 0.094 | 0.110 |
| b | 0.60 | 0.80 | 0.024 | 0.031 |
| b2 | 0.60 | 0.90 | 0.024 | 0.035 |
| С | = | 0.60 | - | 0.024 |
| D | 8.30 | 8.70 | 0.327 | 0.342 |
| d1 | 14.70 | 15.30 | 0.579 | 0.602 |
| d2 | 2.90 | 3.10 | 0.114 | 0.122 |
| d3 | 3.30 | 3.70 | 0.130 | 0.146 |
| Е | 9.70 | 10.30 | 0.382 | 0.406 |
| е | 2.50 | 2.70 | 0.098 | 0.106 |
| L | 13.40 | 13.80 | 0.528 | 0.543 |
| L1 | 1.00 | 2.80 | 0.039 | 0.110 |
| ØP | 3.00 | 3.40 | 0.118 | 0.134 |

ECN: E20-0684-Rev. D, 28-Dec-2020

DWG: 6021



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